



CSP-30 Lead Free RoHS Profile

Total Mass of the Unit specified (g)	Product / Component Description	Breakdown of product / component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass (mg)	PPM	Additional Information
0.022	30 Ball CSP	IC Chip	Silicon doped with aluminium	Silicon (Si)	7440-21-3	15.87943	722,909	
		IC Chip	Silicon doped with aluminium	Aluminium (Al)	7429-90-5	0.00949	432	
		Metalization	UBM	Aluminium (Al)	7429-90-5	0.00589	268	
		Metalization	UBM	Nickel (Ni)	7440-02-0	0.00295	134	
		Metalization	UBM	Vanadium (V)	7440-62-2	0.00295	134	
		Metalization	UBM	Copper (Cu)	7440-50-8	0.02347	1,069	
		Metalization	BCB			0.03566	1,623	Cyclotene 4022-35
		IC Solderball	Solderball	Tin (Sn)	7440-31-5	5.73596	261,129	
		IC Solderball	Solderball	Silver (Ag)	7440-22-4	0.24022	10,936	
		IC Solderball	Solderball	Copper (Cu)	7440-50-8	0.03	1,366	

Total mass (mg)	21.966
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